SPECIFICATIONS FOR NICHIA CHIP TYPE GREEN LED MODEL: NSCG100AT

NICHIA CORPORATION

1.SPECIFICATIONS

(1) Absolute Maximum Ratings

 $(Ta=25^{\circ}C)$

<u>, </u>			<u> </u>
Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	IF	30	mA
Pulse Forward Current	IFP	100	mA
Reverse Voltage	VR	5	V
Power Dissipation	PD	120	mW
Operating Temperature	Topr	-30 ∼ + 85	°C
Storage Temperature	Tstg	-40 ∼ +100	°C
Soldering Temperature	Tsld	Reflow Soldering: 260°C f	or 10sec.
		Hand Soldering : 350°C f	for 3sec.

IFP Conditions : Pulse Width ≤ 10 msec. and Duty $\leq 1/10$

(2) Initial Electrical/Optical Characteristics

 $(Ta=25^{\circ}C)$

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Item		Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage		VF	IF=20[mA]	-	3.5	4.0	V
Reverse Current	_	Ir	$V_R = 5[V]$	1	-	50	μΑ
	Rank T	Iv	IF=20[mA]	560	640	780	mcd
Luminous Intensity	Rank S	Iv	I _F =20[mA]	390	460	560	mcd
	Rank R	Iv	I _F =20[mA]	280	320	390	mcd

^{*} Luminous Intensity Measurement allowance is \pm 10%.

Color Ranks

 $(I_F=20mA T_a=25^{\circ}C)$

		Ran	ık G	
X	0.14	0.14	0.22	0.22
y	0.64	0.74	0.74	0.64

		Ran	k H	
X	0.21	0.21	0.28	0.28
y	0.65	0.73	0.73	0.65

^{*} Color Coordinates Measurement allowance is ± 0.01 .

2.TYPICAL INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS

Please refer to figure's page.

3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to figure's page.

Material as follows; Package : Ceramics

Encapsulating Resin : Silicone Resin Electrodes : Au Plating

^{*} One delivery will include up to two color ranks and three luminous intensity ranks of the products. The quantity-ratio of the ranks is decided by Nichia.

4.PACKAGING

· The LEDs are packed in cardboard boxes after taping.

Please refer to figure's page.

The label on the minimum packing unit shows; Part Number, Lot Number, Ranking, Quantity

- · In order to protect the LEDs from mechanical shock, we pack them in cardboard boxes for transportation.
- The LEDs may be damaged if the boxes are dropped or receive a strong impact against them, so precautions must be taken to prevent any damage.
- · The boxes are not water resistant and therefore must be kept away from water and moisture.
- · When the LEDs are transported, we recommend that you use the same packing method as Nichia.

5.LOT NUMBER

The first six digits number shows **lot number**.

The lot number is composed of the following characters;

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    ○□×××× - △■
    ○ - Year (3 for 2003, 4 for 2004)
    □ - Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)
    ×××× - Nichia's Product Number
    △ - Ranking by Color Coordinates
    ■ - Ranking by Luminous Intensity
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6.RELIABILITY

(1) TEST ITEMS AND RESULTS

m T.	Standard	m . g . tv:	37.	Number of
Test Item	Test Method	Test Conditions	Note	Damaged
Resistance to	JEITA ED-4701	Tsld=260°C, 10sec.	2 times	0/50
Soldering Heat	300 301	(Pre treatment 30°C,70%,168hrs.)		
(Reflow Soldering)				
Solderability	JEITA ED-4701	Tsld= 215 ± 5 °C, 3sec.	1 time	0/50
(Reflow Soldering)	300 303	(Lead Solder)	over 95%	
Thermal Shock	JEITA ED-4701	0°C ~ 100°C	20 cycles	0/50
	300 307	15sec. 15sec.		
Temperature Cycle	JEITA ED-4701	-40 °C ~ 25 °C ~ 100 °C ~ 25 °C	100 cycles	0/50
	100 105	30min. 5min. 30min. 5min.		
Moisture Resistance Cyclic	JEITA ED-4701	$25^{\circ}\text{C} \sim 65^{\circ}\text{C} \sim -10^{\circ}\text{C}$	10 cycles	0/50
	200 203	90%RH 24hrs./1cycle		
High Temperature Storage	JEITA ED-4701 200 201	Ta=100°C	1000 hrs.	0/50
Temperature Humidity	JEITA ED-4701	Ta=60°C, RH=90%	1000 hrs.	0/50
Storage	100 103	,		
Low Temperature Storage	JEITA ED-4701 200 202	Ta=-40°C	1000 hrs.	0/50
Steady State Operating Life Condition 1		Ta=25°C, IF=20mA	1000 hrs.	0/50
Steady State Operating Life Condition 2		Ta=25°C, IF=30mA	1000 hrs.	0/50
Steady State Operating Life of High Temperature		Ta=85°C, IF=7.5mA	1000 hrs.	0/50
Steady State Operating Life of High Humidity Heat		60°C, RH=90%, IF=20mA	500 hrs.	0/50
Steady State Operating Life of Low Temperature		Ta=-30°C, IF=20mA	1000 hrs.	0/50
Vibration	JEITA ED-4701 400 403	$100 \sim 2000 \sim 100$ Hz Sweep 4min. 200m/s ² 3direction, 4cycles	48min.	0/50
Substrate Bending	JEITA ED-4702	3mm, 5 ± 1 sec.	1 time	0/50
Stick	JEITA ED-4702	$5N$, 10 ± 1 sec.	1 time	0/50

(2) CRITERIA FOR JUDGING THE DAMAGE

			Criteria for	Judgement
Item	Symbol	Test Conditions	Min.	Max.
Forward Voltage	VF	IF=20mA	-	U.S.L.*)× 1.1
Reverse Current	Ir	V _R =5V	-	$U.S.L.*) \times 2.0$
Luminous Intensity	Iv	I _F =20mA	$L.S.L.**) \times 0.7$	-

^{*)} U.S.L.: Upper Standard Level

^{**)} L.S.L.: Lower Standard Level

7.CAUTIONS

(1) Moisture Proof Package

- · When moisture is absorbed into the SMT package it may vaporize and expand during soldering. There is a possibility that this can cause exfoliation of the contacts and damage to the optical characteristics of the LEDs. For this reason, the moisture proof package is used to keep moisture to a minimum in the package.
- The moisture proof package is made of an aluminum moisture proof bag with a zipper. A package of a moisture absorbent material (silica gel) is inserted into the aluminum moisture proof bag. The silica gel changes its color from blue to pink as it absorbs moisture.

(2) Storage

· Storage Conditions

Before opening the package:

The LEDs should be kept at 30°C or less and 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

After opening the package:

The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours (7days) after opening the package. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.

· If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : more than 24 hours at $65 \pm 5^{\circ}$ C

- · Nichia LED electrode sections are comprised of a gold plated. The gold surface may be affected by environments which contain corrosive gases and so on. Please avoid conditions which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operations. It is recommended that the User use the LEDs as soon as possible.
- · Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.

(3) Heat Generation

- Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.
- The operating current should be decided after considering the ambient maximum temperature of LEDs.

(4) Soldering Conditions

• The LEDs can be soldered in place using the reflow soldering method. Nichia cannot make a guarantee on the LEDs after they have been assembled using the dip soldering method.

· Recommended soldering conditions

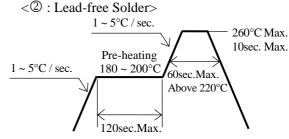
	Reflow Solderin	Hand S	oldering	
	Lead Solder	Lead-free Solder		
Pre-heat	120 ~ 150°C	180 ~ 200°C	Temperature	350°C Max.
Pre-heat time	120 sec. Max.	120 sec. Max.	Soldering time	3 sec. Max.
Peak temperature	240°C Max.	260°C Max.		(one time only)
Soldering time Condition	10 sec. Max. refer to	10 sec. Max. refer to		
	Temperature - profile ①.	Temperature - profile $②$. (N_2 reflow is recommended.)		

* After reflow soldering rapid cooling should be avoided.

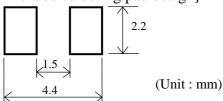
[Temperature-profile (Surface of circuit board)] <① : Lead Solder>

 $2.5 \sim 5^{\circ}\text{C / sec.}$ Pre-heating 120 ~ 150°C 60sec.Max.
Above 200°C 120sec.Max.

Use the conditions shown to the under figure.



[Recommended soldering pad design]



Use the following conditions shown in the figure.

- · Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the chip mounter, the picking up nozzle that does not affect the silicone resin should be used.
- · Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- · Reflow soldering should not be done more than two times.
- · When soldering, do not put stress on the LEDs during heating.
- · After soldering, do not warp the circuit board.

(5) Cleaning

- It is recommended that isopropyl alcohol be used as a solvent for cleaning the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not. Freon solvents should not be used to clean the LEDs because of worldwide regulations.
- · Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

(6) Static Electricity

- · Static electricity or surge voltage damages the LEDs.

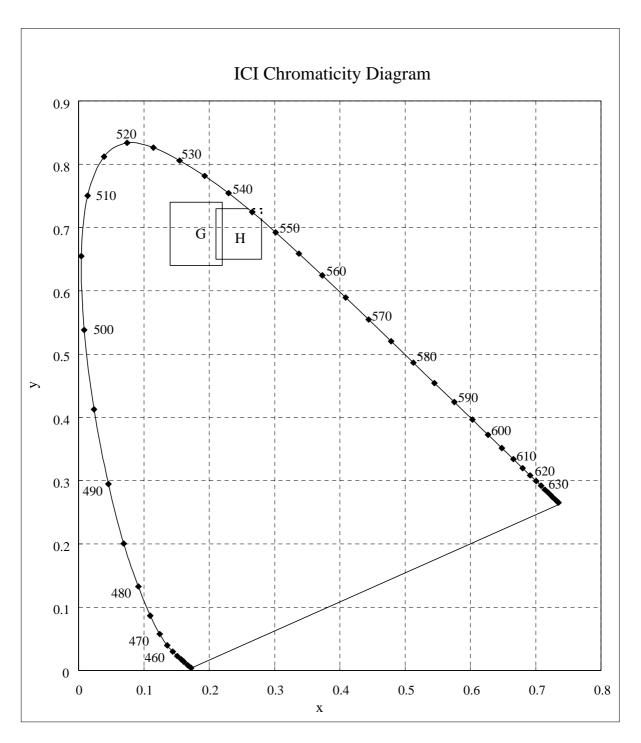
 It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
- · All devices, equipment and machinery must be properly grounded.

 It is recommended that measures be taken against surge voltage to the equipment that mounts the LEDs.
- · When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a VF test at a lower current (below 1mA is recommended).
- · Damaged LEDs will show some unusual characteristics such as the leak current remarkably increases, the forward voltage becomes lower, or the LEDs do not light at the low current.

Criteria: (VF > 2.0V at IF=0.5mA)

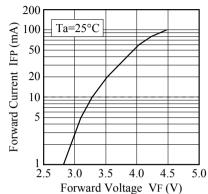
(7) Others

- · Care must be taken to ensure that the reverse voltage will not exceed the absolute maximum rating when using the LEDs with matrix drive.
- The LED light output is strong enough to injure human eyes. Precautions must be taken to prevent looking directly at the LEDs with unaided eyes for more than a few seconds.
- · Flashing lights have been known to cause discomfort in people; you can prevent this by taking precautions during use. Also, people should be cautious when using equipment that has had LEDs incorporated into it.
- The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances). Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control systems, automobiles, traffic control equipment, life support systems and safety devices).
- · User shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from Nichia. When defective LEDs are found, the User shall inform Nichia directly before disassembling or analysis.
- The formal specifications must be exchanged and signed by both parties before large volume purchase begins.
- · The appearance and specifications of the product may be modified for improvement without notice.

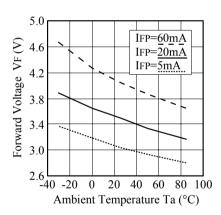


* Color Coordinates Measurement allowance is ± 0.01 .

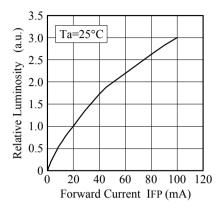
■ Forward Voltage vs.



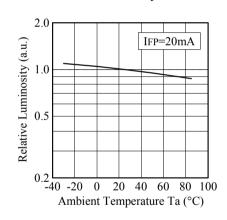
■ Ambient Temperature vs. Forward Voltage



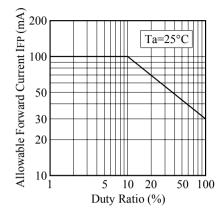
■ Forward Current vs. Relative Luminosity



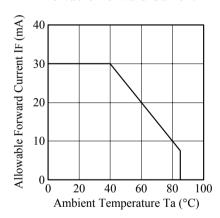
■ Ambient Temperature vs. Relative Luminosity



■ Duty Ratio vs. Allowable Forward Current

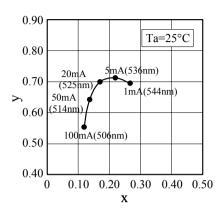


■ Ambient Temperature vs. Allowable Forward Current

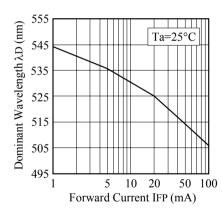


Model NSCG100A NICHIA CORPORATION Title TYP.CHARACTERISTICS 050322538201 No.

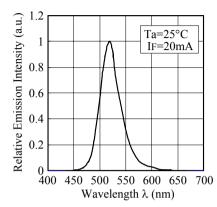
Forward Current vs.
Chromaticity Coordinate (λD)



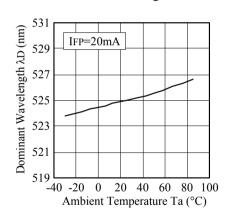
■ Forward Current vs. Dominant Wavelength



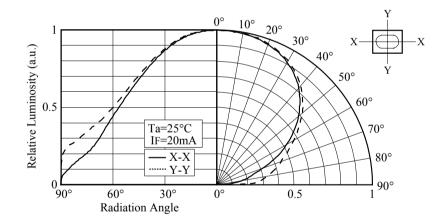
■ Spectrum



■ Ambient Temperature vs. Dominant Wavelength



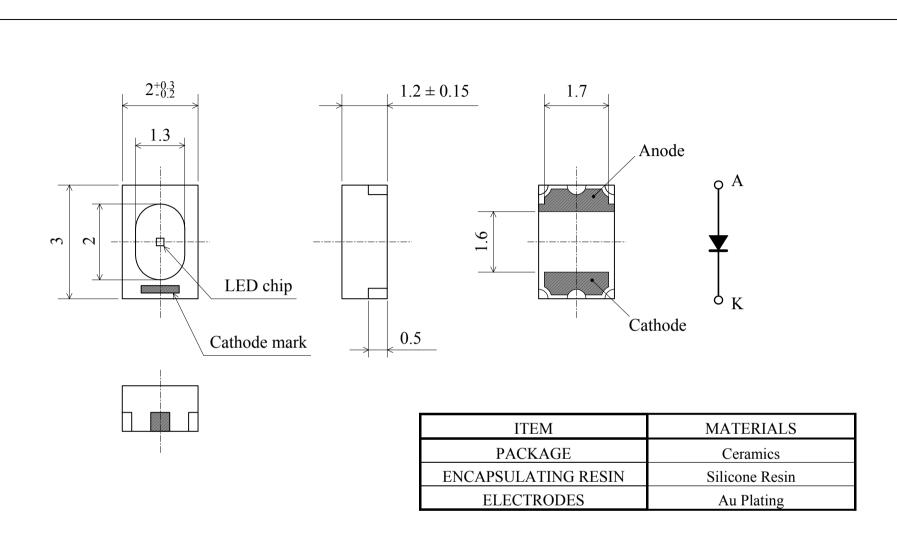
■ Directivity (NSCG100A)



NICHIA C	ORPORATION
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	Mode	el NSCG100A	\
1	Title	TYP.CHARACTERISTICS	
	No.	011003107771	

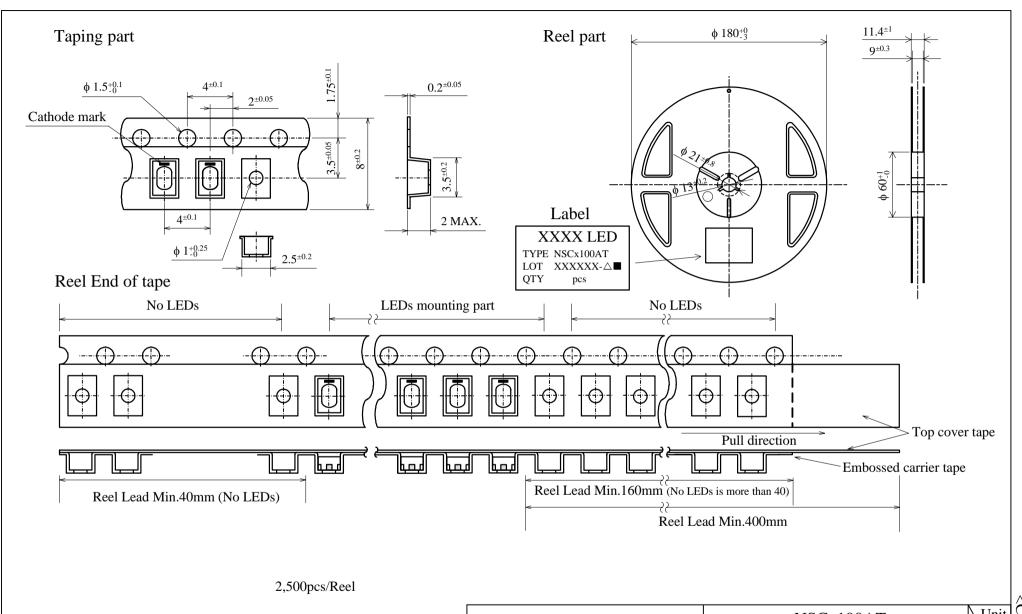
Nichia STSE-CC2010B <Cat.No.040528>



	Model	NSCG100A	Unit
NICHIA CORPORATION	Title	OUTLINE DIMENSIONS	10/1 Scale
	No.	011004107781	Allow ±0.2

Nichia STSE-CC2010B <Cat.No.040528>



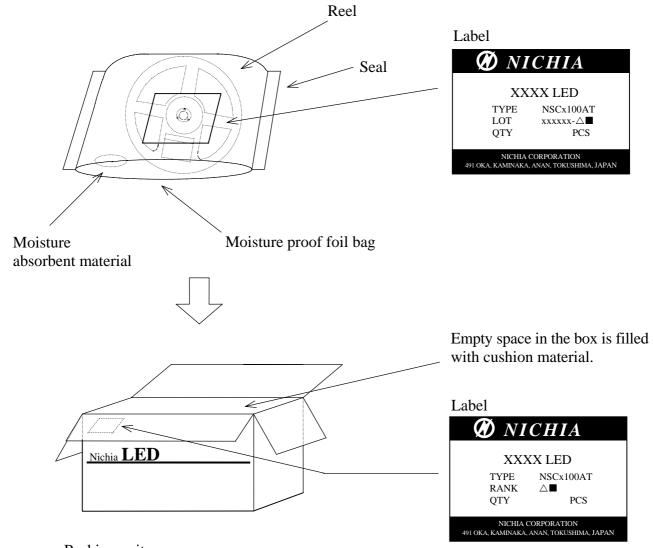


Taping is based on the JIS C 0806: Packaging of Electronic

Components on Continuous Tapes.

	Model	NSCx100AT	Unit A STS
NICHIA CORPORATION	Title	TAPING DIMENSIONS	No.040; Scale Sc
	No.	030920316191	Allow 57 28 28 28 28 28 28 28 2

The reel and moisture absorbent material are put in the moisture proof foil bag and then heat sealed.



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	Reel/bag	Quantity/bag (pcs)
Moisture proof foil bag	1reel	2,500 MAX.

Cardboard box	Dimensions (mm)	Reel/box	Quantity/box (pcs)
Cardboard box S	$270\times280\times100\times4t$	4reel MAX.	10,000 MAX.
Cardboard box M	$270\times280\times200\times4t$	10reel MAX.	25,000 MAX.
Cardboard box L	270×280×300×4t	16reel MAX.	40,000 MAX.

	Model	NSCx100AT	
NICHIA CORPORATION	Title	PACKING	
	No.	030909315761	